



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20240621001.1**

**Qualification of TIPI as additional Assembly site for select devices  
Change Notification / Sample Request**

**Date:** June 21, 2024

**To:** Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20240621001.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
DLPC1438ZEZ	NULL
DLPC3420ZVB	NULL
DLPC3421ZVB	NULL
DLPC3426ZVB	NULL
DLPC3435CZEZ	NULL
DLPC3436CZVB	NULL
DLPC3438CZEZ	NULL
DLPC3439CZEZ	NULL
DLPC3470CZEZ	NULL
DLPC3478CZEZ	NULL
DLPC3479CZEZ	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20240621001.1	<b>PCN Date:</b>	June 21, 2024
<b>Title:</b>	Qualification of TIPI as an additional Assembly site for select devices		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	September 19, 2024	<b>Sample requests accepted until:</b>	July 21, 2024
<b>*Sample requests received after July 21, 2024 will not be supported.</b>			
<b>Change Type:</b>			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/> Wafer Bump Material
<input type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/> Wafer Fab Process

### PCN Details

#### Description of Change:

Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for devices listed below in the product affected section. Construction differences and current assembly site as follows:

ASECL		TIPI
Mount Compound	SID# EPND2100A001B	4205412
Mold Compound	SID# 1800874111	4208515

#### Reason for Change:

Supply continuity

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Impact on Environmental Ratings:

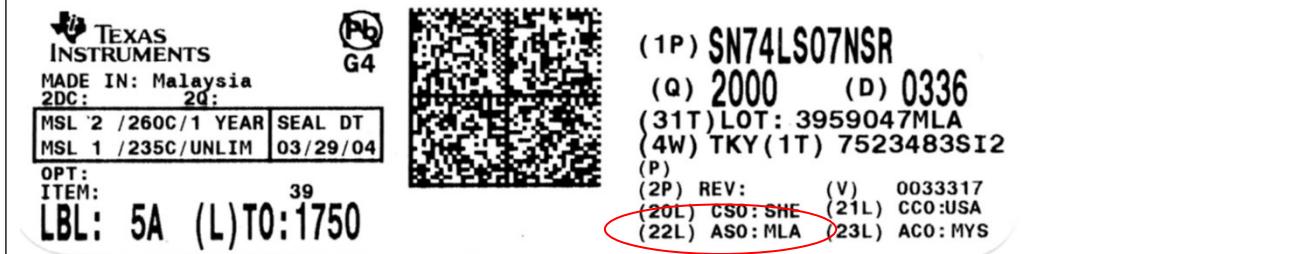
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

#### Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASECL	UAJ	TWN	Chung-Li
<b>TIPI</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio City</b>

Sample product shipping label (not actual product label)



<b>Product Affected:</b>			
DLPC1438ZEZ	DLPC3426ZVB	DLPC3435CZEZ	DLPC3440CZEZ
DLPC1439ZEZ	DLPC3430CZVBR	DLPC3436CZVB	DLPC3470CZEZ
DLPC150ZEZ	DLPC3432CZVB	DLPC3437CZEZ	DLPC3478CZEZ
DLPC3420ZVB	DLPC3433CZVB	DLPC3438CZEZ	DLPC3479CZEZ
DLPC3421ZVB	DLPC3434CZVB	DLPC3439CZEZ	

## Qualification Report

Approval Date 22 April 2024

### Product Attributes

Qualification/QBS Devices	Qual: DLPC3436CZVB DLPC3437CZEZ	QBS Device: CD3215CX00ZBHR	QBS Device: LMK04616ZCRR	QBS Device: MSP430FR5994IZVW	QBS Device: OMAP5912ZVL	QBS Device: TMP5703137BZWTQQ1	QBS Device: TPS659038XZWSRQ1	QBS Device: TUSB1310ZAY	QBS Device: 781962BZCZ
Assembly Site	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI
Package Family	NFBGA	NFBGA	NFBGA	NFBGA	NFBGA	NFBGA	NFBGA	NFBGA	NFBGA
Pin Count	176 / 201	96	144	87	289	337	169	175	324
Package Designator	ZVB / ZEZ	ZBH	ZCR	ZVV	ZVL	ZWT	ZWS	ZAY	ZCZ
Moisture Sensitivity Level	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C	LEVEL3-260C
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	TSMC-F12	RFAB	FFAB	DMOS6	DMOS6	TSMC-F14	RFAB	DMOS6	UMC-F12
Wafer Process	1018C014	LBCBLV	BICMOS13	HPE035	1533C035	12F021	LBC7	111BC021	111BC014

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	QBS Device: CD3215CX00ZBHR	QBS Device: LMK04616ZCRR	QBS Device: MSP430FR5994IZVW	QBS Device: OMAP5912ZVL	QBS Device: TMP5703137BZWTQQ1	QBS Device: TPS659038XZWSRQ1	QBS Device: TUSB1310ZAY	QBS Device: 781962BZCZ
PC	Preconditioning	L3-260C	3/924/0	3/924/0	3/1155/0	3/924/0	3/924/0	3/693/0	3/1155/0	3/924/0
AC	Autoclave, 121C	96 Hours	---	---	3/231/0	---	---	---	---	---
UHAST	UHAST, 110C/85%RH	264 Hours	3/231/0	3/231/0	---	3/231/0	3/231/0	3/231/0	---	3/231/0
UHAST	UHAST, 130C/85%RH	96 Hours	---	---	---	---	---	---	3/231/0	---
HAST	THB, 85C/85%RH	1000 Hours	---	---	---	---	3/231/0	3/231/0	---	3/231/0
HAST	BHAST, 110C/85%RH	264 Hours	3/231/0	3/231/0	3/231/0	3/231/0	---	---	---	---
HAST	BHAST, 130C/85%RH	96 Hours	---	---	---	---	---	---	3/231/0	---
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	---	---	3/231/0	---	---	3/231/0	---	---
HTOL	High Temp Operating Life, 105C	1000 Hours	---	1/77/0	---	---	---	3/231/0	---	---
HTOL	High Temp Operating Life, 115C	1000 Hours	---	1/77/0	---	---	---	3/231/0	---	---
HTOL	High Temp Operating Life, 125C	1000 Hours	3/231/0	---	3/231/0	---	3/231/0	---	3/231/0	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	---	---	---	---	3/2400/0	---	3/1833/0	3/2400/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	1/77/0	3/231/0	3/231/0	3/135/0	3/231/0	3/135/0	3/135/0
PTC	Power Temp Cycle, -40C/105C	1000 Cycles	---	---	---	---	---	3/135/0	---	---
ED	Electrical Characterization	Datasheet	3/90/0	1/30/0	3/90/0	1/30/0	3/90/0	3/90/0	3/90/0	3/90/0
TPI	Thermal Path Integrity	500 Cycles	---	---	---	3/36/0	---	---	---	---
FLAM	Flammability (UL94 V-0)	--	3/PASS	---	---	---	---	---	---	---
FLAM	Flammability (IEC 695-2-2)	--	3/PASS	---	---	---	---	---	---	---
FLAM	Flammability (UL-1694)	--	3/PASS	---	---	---	---	---	---	---
CDM	ESD, Charged Device	250V	3/PASS	1/PASS	1/PASS	1/PASS	1/PASS	1/PASS	3/PASS	3/PASS
HBM	ESD, Human Body	1000V	3/PASS	1/PASS	1/PASS	1/PASS	1/PASS	1/PASS	3/PASS	3/PASS
LU	Latch-up	Per JESD78	3/PASS	1/PASS	1/PASS	1/PASS	1/PASS	1/PASS	3/PASS	3/PASS
MQ	Assembly MQ	Lots	3/PASS	3/PASS	3/PASS	3/PASS	3/PASS	3/PASS	3/PASS	3/PASS
SBS	Solder Ball Shear	Balls	3/540/0	1/80/0	---	---	---	3/150/0	3/240/0	3/240/0
PD	Physical Dimensions	Devices	3/15/0	---	---	---	---	3/30/0	---	3/30/0
SD	Pb Free		3/66/0	---	---	3/66/0	---	---	---	---
MSL	Level 3-260C		3/36/0	3/36/0	3/36/0	3/36/0	3/36/0	3/36/0	3/36/0	3/36/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
Green/Pb-free Status:  
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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